

PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad is



Fig.1 Forward Current Derating Curve

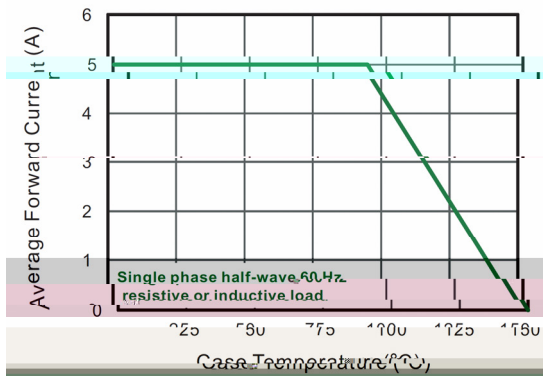


Fig.2 Typical Reverse Characteristics

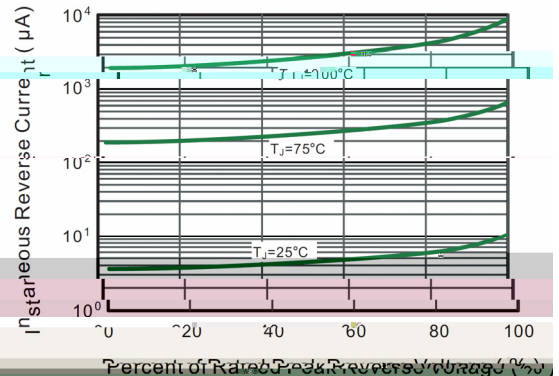


Fig.3 Typical Forward Characteristic

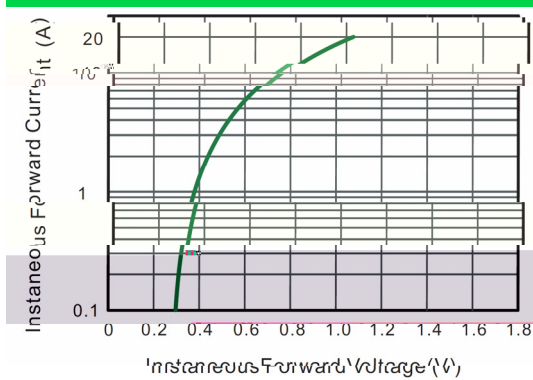


Fig.4 Typical Junction Capacitance

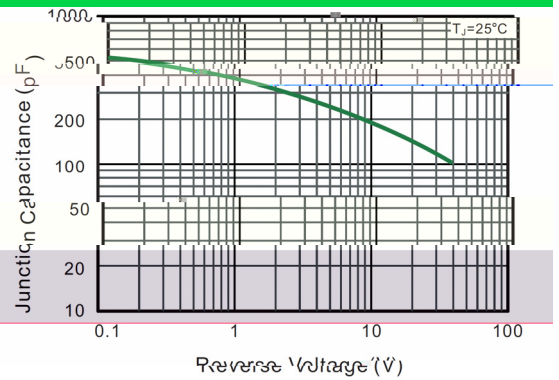


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

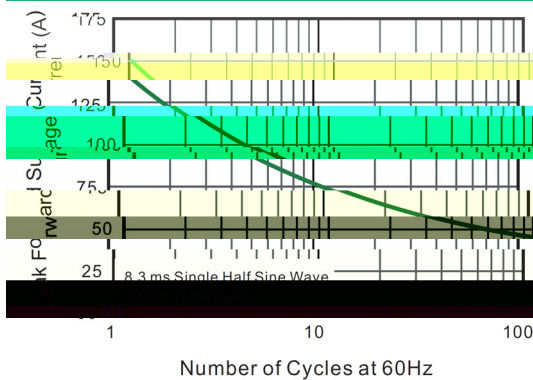
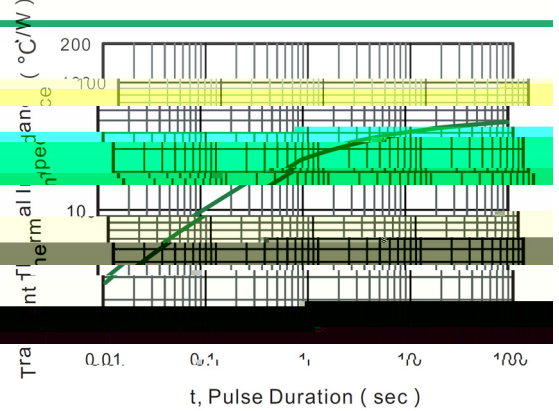
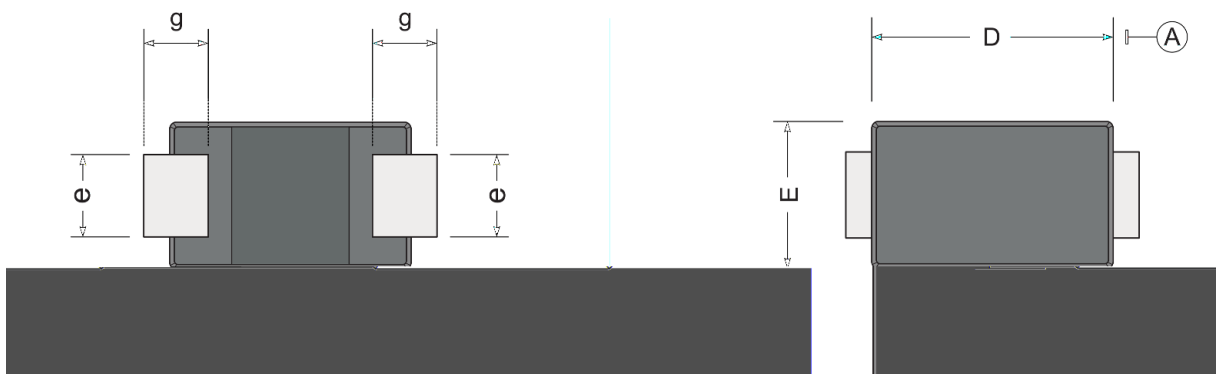
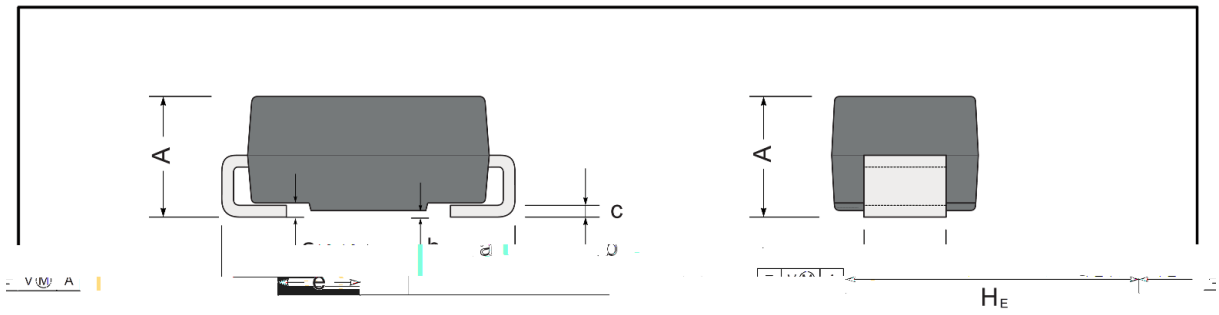


Fig.6 Typical Transient Thermal Impedance

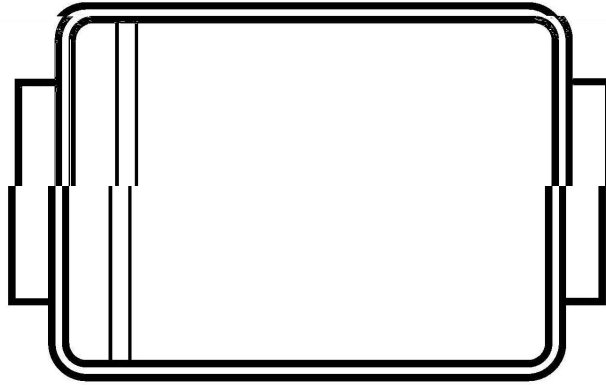


SMA



D	E	H _E	c	e	g	b	a
4.5	2.7	5.2	0.31	1.6	1.5	0.2	0.3
4.0	2.3	4.7	0.15	1.3	0.9	0.05	

UNIT		A
mm	max	2.2
	min	1.9
mil	max	87
	min	75



Temperature Profile for IR Reflow Soldering(Pb-Free)

